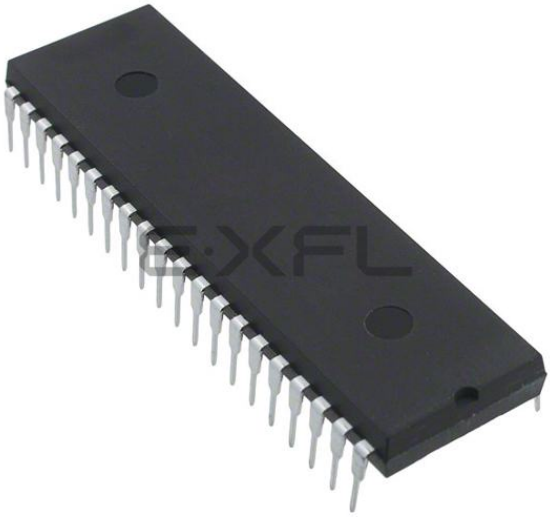

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	24MHz
Connectivity	SPI, UART/USART
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	12KB (12K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89s8253-24pc

3.5 PWRGND

Ground for the 42-PDIP which connects only the I/O Pad Drivers. PWRGND and GND are weakly connected through the common silicon substrate, but not through any metal links. The application board **must** connect both GND and PWRGND to the board ground.

3.6 Port 0

Port 0 is an 8-bit open drain bi-directional I/O port. As an output port, each pin can sink six TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 can also be configured to be the multiplexed low-order address/data bus during accesses to external program and data memory. In this mode, P0 has internal pull-ups.

Port 0 also receives the code bytes during Flash programming and outputs the code bytes during program verification. **External pull-ups are required during program verification.**

3.7 Port 1

Port 1 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 1 output buffers can sink/source six TTL inputs. When 1s are written to Port 1 pins, they are pulled high by the weak internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (I_{IL},150 µA typical) because of the weak internal pull-ups.

Some Port 1 pins provide additional functions. P1.0 and P1.1 can be configured to be the timer/counter 2 external count input (P1.0/T2) and the timer/counter 2 trigger input (P1.1/T2EX), respectively. Furthermore, P1.4, P1.5, P1.6, and P1.7 can be configured as the SPI slave port select, data input/output and shift clock input/output pins as shown in the following table.

Port Pin	Alternate Functions
P1.0	T2 (external count input to Timer/Counter 2), clock-out
P1.1	T2EX (Timer/Counter 2 capture/reload trigger and direction control)
P1.4	$\overline{SS}$ (Slave port select input)
P1.5	MOSI (Master data output, slave data input pin for SPI channel)
P1.6	MISO (Master data input, slave data output pin for SPI channel)
P1.7	SCK (Master clock output, slave clock input pin for SPI channel)

Port 1 also receives the low-order address bytes during Flash programming and verification.

3.8 Port 2

Port 2 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 2 output buffers can sink/source six TTL inputs. When 1s are written to Port 2 pins, they are pulled high by the weak internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current (I_{IL},150 µA typical) because of the weak internal pull-ups.

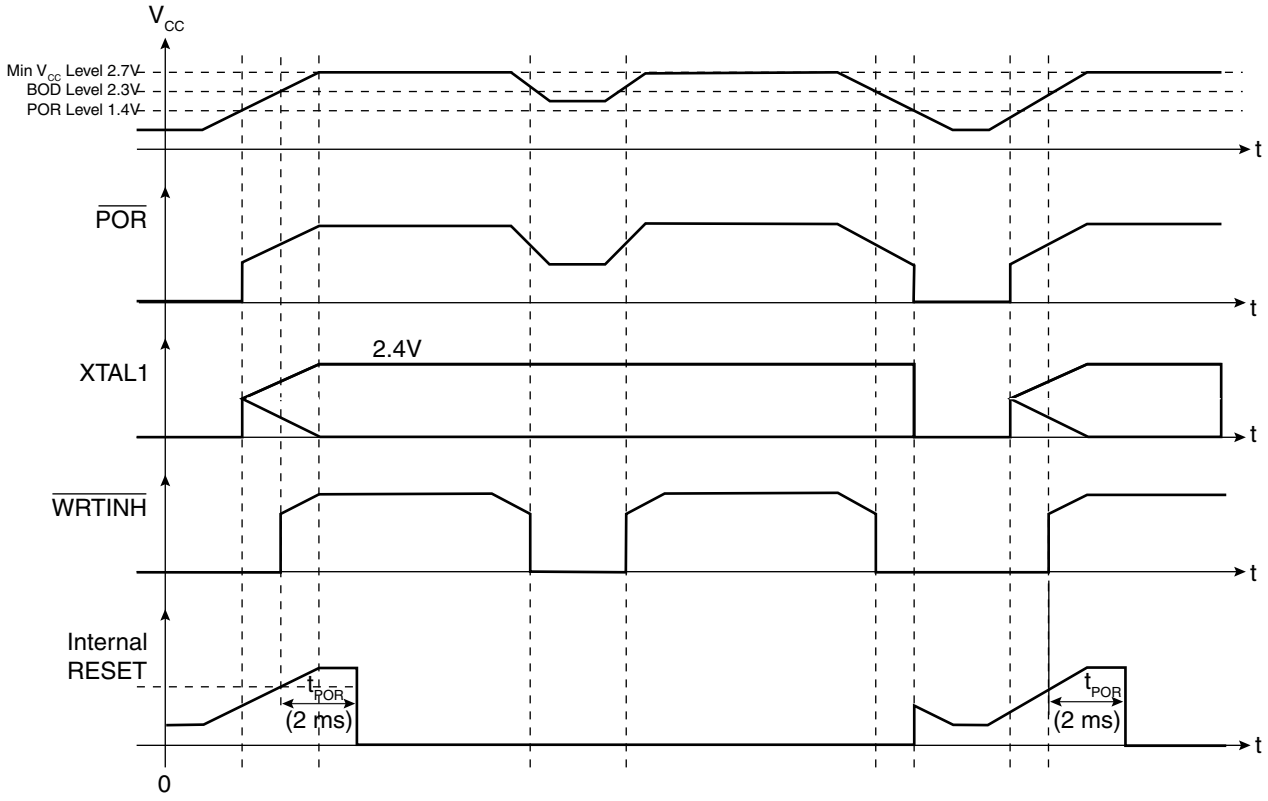
Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application, Port 2 uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during Flash programming and verification.

7. Power-On Reset

A Power-On Reset (POR) is generated by an on-chip detection circuit. The detection level is nominally 1.4V. The POR is activated whenever V_{CC} is below the detection level. The POR circuit can be used to trigger the start-up reset or to detect a supply voltage failure in devices without a brown-out detector. The POR circuit ensures that the device is reset from power-on. When V_{CC} reaches the Power-on Reset threshold voltage, the POR delay counter determines how long the device is kept in POR after V_{CC} rise, nominally 2 ms. The POR signal is activated again, without any delay, when V_{CC} falls below the POR threshold level. A Power-On Reset (i.e. a cold reset) will set the POF flag in PCON.

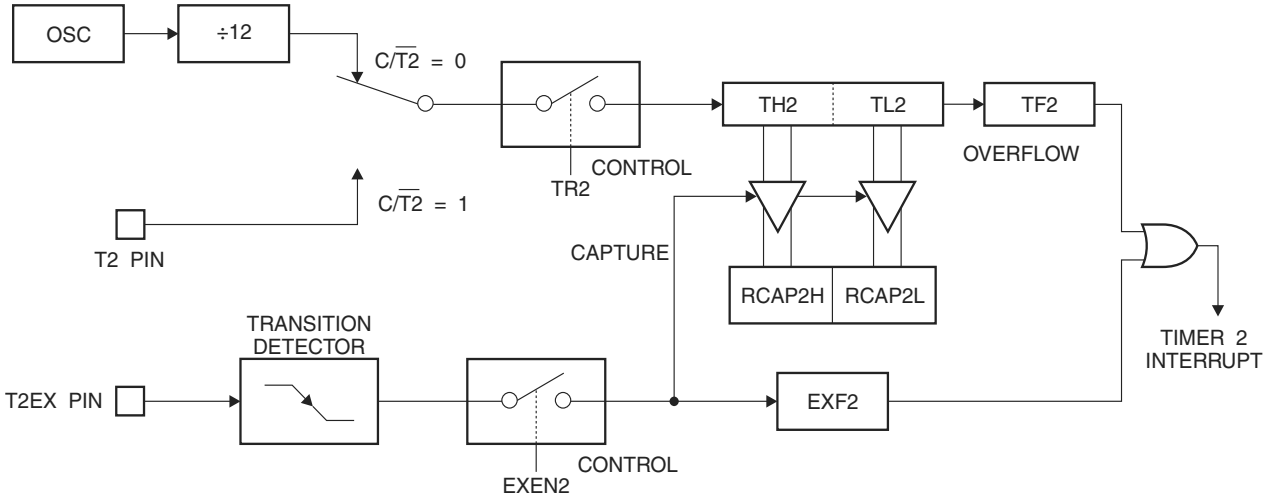
Figure 7-1. Power-up and Brown-out Detection Sequence



7.1 Memory Brown-out Protection

The AT89S8253 has an on-chip Brown-out Detection (BOD) circuit for monitoring the V_{CC} level during operation by comparing it to a fixed trigger level of nominally 2.2V (2.4V max). The purpose of the BOD is to ensure that if V_{CC} fails or dips, the Flash or EEPROM memories cannot be erased/written at voltages too low for programming. At powerup the V_{CC} level must pass the BOD threshold before execution starts. When V_{CC} decreases to a value below the trigger level, the $\overline{\text{WRTINH}}$ bit in EECON is activated and futher programming of the Flash/EEPROM is restricted. When V_{CC} increases above the trigger level, the BOD delay counter blocks programming until after the timeout period has expired in approximately 2 ms. The BOD does not reset the system as shown in Figure 7-1. To protect the system from errors induced by incorrect execution at lower voltages an external BOD circuit may be required.

Figure 10-1. Timer 2 in Capture Mode



10.3 Auto-reload (Up or Down Counter)

Timer 2 can be programmed to count up or down when configured in its 16-bit auto-reload mode. This feature is invoked by the DCEN (Down Counter Enable) bit located in the SFR T2MOD (see Table 10-3). Upon reset, the DCEN bit is set to 0 so that timer 2 will default to count up. When DCEN is set, Timer 2 can count up or down, depending on the value of the T2EX pin.

Table 10-3. T2MOD – Timer 2 Mode Control Register

T2MOD Address = 0C9H — Reset Value = XXXX XX00B

Not Bit Addressable

	–	–	–	–	–	–	T2OE	DCEN
Bit	7	6	5	4	3	2	1	0

Symbol	Function
–	Not implemented, reserved for future use.
T2OE	Timer 2 Output Enable bit.
DCEN	When set, this bit allows Timer 2 to be configured as an up/down counter.

Figure 10-2 shows Timer 2 automatically counting up when DCEN = 0. In this mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 counts up to 0FFFFH and then sets the TF2 bit upon overflow. The overflow also causes the timer registers to be reloaded with the 16-bit value in RCAP2H and RCAP2L. The values in RCAP2H and RCAP2L are preset by software. If EXEN2 = 1, a 16-bit reload can be triggered either by an overflow or by a 1-to-0 transition at external input T2EX. This transition also sets the EXF2 bit. Both the TF2 and EXF2 bits can generate an interrupt if enabled.

Setting the DCEN bit enables Timer 2 to count up or down, as shown in Figure 10-3. In this mode, the T2EX pin controls the direction of the count. A logic 1 at T2EX makes Timer 2 count up. The timer will overflow at 0FFFFH and set the TF2 bit. This overflow also causes the 16-bit

value in RCAP2H and RCAP2L to be reloaded into the timer registers, TH2 and TL2, respectively.

A logic 0 at T2EX makes Timer 2 count down. The timer underflows when TH2 and TL2 equal the values stored in RCAP2H and RCAP2L. The underflow sets the TF2 bit and causes 0FFFFH to be reloaded into the timer registers.

The EXF2 bit toggles whenever Timer 2 overflows or underflows and can be used as a 17th bit of resolution. In this operating mode, EXF2 does not flag an interrupt.

Figure 10-2. Timer 2 in Auto Reload Mode (DCEN = 0)

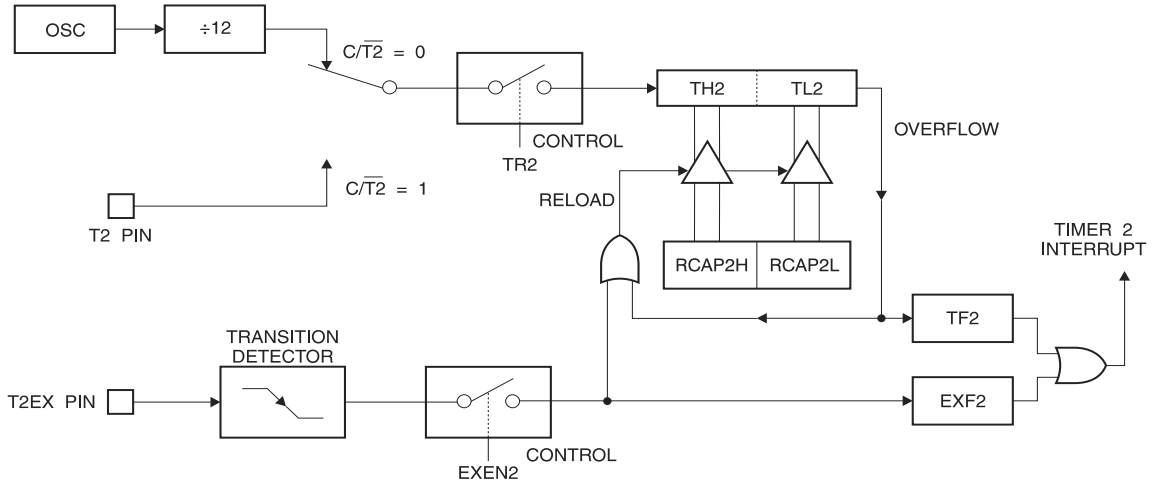
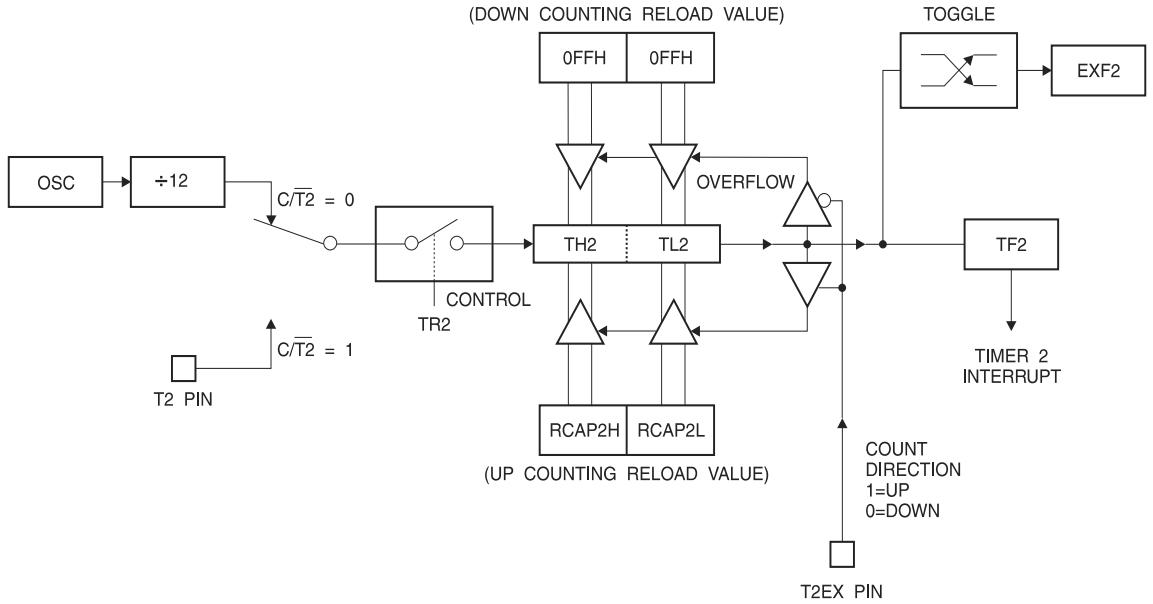


Figure 10-3. Timer 2 Auto Reload Mode (DCEN = 1 Timer 2 Auto Reload Mode (DCEN = 1)



Timer 2 as a baud rate generator is shown in Figure 10-4. This figure is valid only if RCLK or TCLK = 1 in T2CON. Note that a rollover in TH2 does not set TF2 and will not generate an interrupt. Note too, that if EXEN2 is set, a 1-to-0 transition in T2EX will set EXF2 but will not cause a reload from (RCAP2H, RCAP2L) to (TH2, TL2). Thus when Timer 2 is in use as a baud rate generator, T2EX can be used as an extra external interrupt.

Note that when Timer 2 is running (TR2 = 1) as a timer in the baud rate generator mode, TH2 or TL2 should not be read from or written to. Under these conditions, the Timer is incremented every state time, and the results of a read or write may not be accurate. The RCAP2 registers may be read but should not be written to, because a write might overlap a reload and cause write and/or reload errors. The timer should be turned off (clear TR2) before accessing the Timer 2 or RCAP2 registers.

12. Programmable Clock Out

A 50% duty cycle clock can be programmed to come out on P1.0, as shown in Figure 12-1. This pin, besides being a regular I/O pin, has two alternate functions. It can be programmed to input the external clock for Timer/Counter 2 or to output a 50% duty cycle clock ranging from 61 Hz to 4 MHz (for a 16 MHz operating frequency).

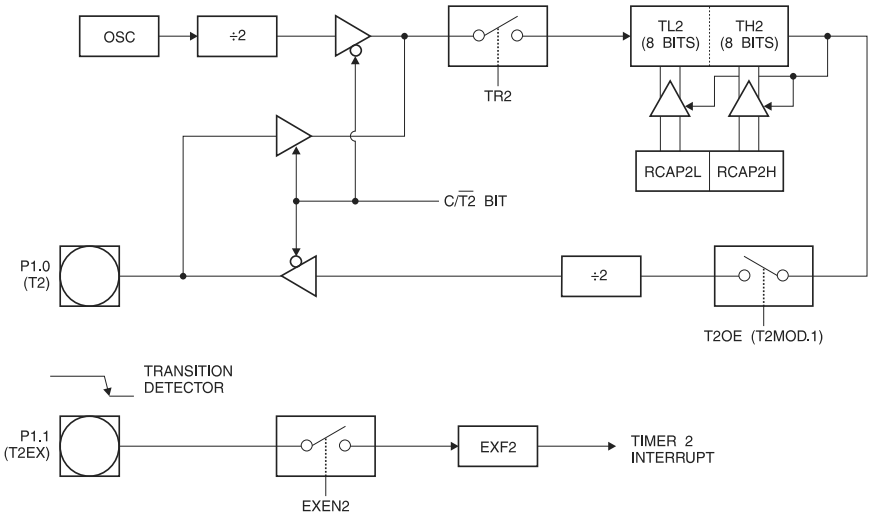
To configure the Timer/Counter 2 as a clock generator, bit C/$\overline{T2}$ (T2CON.1) must be cleared and bit T2OE (T2MOD.1) must be set. Bit TR2 (T2CON.2) starts and stops the timer.

The clock-out frequency depends on the oscillator frequency and the reload value of Timer 2 capture registers (RCAP2H, RCAP2L), as shown in the following equation.

$$\text{Clock Out Frequency} = \frac{\text{Oscillator Frequency}}{4 \times [65536 - (\text{RCAP2H,RCAP2L})]}$$

In the clock-out mode, Timer 2 rollovers will not generate an interrupt. This behavior is similar to when Timer 2 is used as a baud-rate generator. It is possible to use Timer 2 as a baud-rate generator and a clock generator simultaneously. Note, however, that the baud-rate and clock-out frequencies cannot be determined independently from one another since they both use RCAP2H and RCAP2L.

Figure 12-1. Timer 2 in Clock-out Mode



In the previous example SADDR is the same and the SADEN data is used to differentiate between the two slaves. Slave 0 requires a 0 in bit 0 and it ignores bit 1. Slave 1 requires a 0 in bit 1 and bit 0 is ignored. A unique address for slave 0 would be 1100 0010 since slave 1 requires a 0 in bit 1. A unique address for slave 1 would be 1100 0001 since a 1 in bit 0 will exclude slave 0. Both slaves can be selected at the same time by an address which has bit 0 = 0 (for slave 0) and bit 1 = 0 (for slave 1). Thus, both could be addressed with 1100 0000.

In a more complex system the following could be used to select slaves 1 and 2 while excluding slave 0:

Slave 0 SADDR = 1100 0000

SADEN = 1111 1001

Given = 1100 0XX0

Slave 1 SADDR = 1110 0000

SADEN = 1111 1010

Given = 1110 0X0X

Slave 2 SADDR = 1110 0000

SADEN = 1111 1100

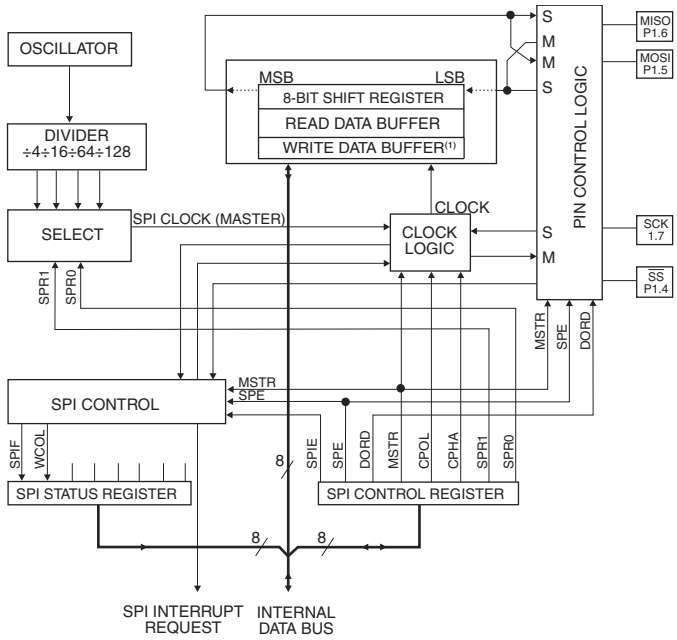
Given = 1110 00XX

In the previous example the differentiation among the 3 slaves is in the lower 3 address bits. Slave 0 requires that bit 0 = 0 and it can be uniquely addressed by 1110 0110. Slave 1 requires that bit 1 = 0 and it can be uniquely addressed by 1110 and 0101. Slave 2 requires that bit 2 = 0 and its unique address is 1110 0011. To select Slaves 0 and 1 and exclude Slave 2, use address 1110 0100, since it is necessary to make bit 2 = 1 to exclude slave 2.

The Broadcast Address for each slave is created by taking the logical OR of SADDR and SADEN. Zeros in this result are trended as don't-cares. In most cases, interpreting the don't-cares as ones, the broadcast address will be FF hexadecimal.

Upon reset SADDR (SFR address 0A9H) and SADEN (SFR address 0B9H) are loaded with 0s. This produces a given address of all "don't cares" as well as a Broadcast address of all "don't cares". This effectively disables the Automatic Addressing mode and allows the microcontroller to use standard 80C51-type UART drivers which do not make use of this feature.

Figure 14-2. SPI Block Diagram



Note: 1. The Write Data Buffer is only used in enhanced SPI mode.

The SPI has two modes of operation: normal (non-buffered write) and enhanced (buffered write). In normal mode, writing to the SPI data register (SPDR) of the master CPU starts the SPI clock generator and the data written shifts out of the MOSI pin and into the MOSI pin of the slave CPU. Transmission may start after an initial delay while the clock generator waits for the next full bit slot of the specified baud rate. After shifting one byte, the SPI clock generator stops, setting the end of transmission flag (SPIF) and transferring the received byte to the read buffer (SPDR). If both the SPI interrupt enable bit (SPIE) and the serial port interrupt enable bit (ES) are set, an interrupt is requested. Note that SPDR refers to either the write data buffer or the read data buffer, depending on whether the access is a write or read. In normal mode, because the write buffer is transparent (and a write access to SPDR will be directed to the shift buffer), any attempt to write to SPDR while a transmission is in progress will result in a write collision with WCOL set. However, the transmission will still complete normally, but the new byte will be ignored and a new write access to SPDR will be necessary.

Enhanced mode is similar to normal mode except that the write buffer holds the next byte to be transmitted. Writing to SPDR loads the write buffer and sets WCOL to signify that the buffer is full and any further writes will overwrite the buffer. WCOL is cleared by hardware when the buffered byte is loaded into the shift register and transmission begins. If the master SPI is currently idle, i.e. if this is the first byte, then after loading SPDR, transmission of the byte starts and WCOL is cleared immediately. While this byte is transmitting, the next byte may be written to SPDR. The Load Enable flag (LDEN) in SPSR can be used to determine when transmission has started. LDEN is asserted during the first four bit slots of a SPI transfer. The master CPU should first check that LDEN is set and that WCOL is cleared before loading the next byte. In enhanced mode, if WCOL is set when a transfer completes, i.e. the next byte is available, then the SPI immediately loads the buffered byte into the shift register, resets WCOL, and continues transmission without stopping and restarting the clock generator. As long as the CPU can keep the write buffer full in this manner, multiple bytes may be transferred with minimal latency between bytes.

Table 15-3. IPH – Interrupt Priority High Register

IPH = B7H — Reset Value = XX00 0000B

Not Bit Addressable

	–	–	PT2H	PSH	PT1H	PX1H	PT0H	PX0H
Bit	7	6	5	4	3	2	1	0

Symbol	Function
PT2H	Timer 2 Interrupt Priority High
PSH	Serial Port Interrupt Priority High
PT1H	Timer 1 Interrupt Priority High
PX1H	External Interrupt 1 Priority High
PT0H	Timer 0 Interrupt Priority High
PX0H	External Interrupt 0 Priority High

Figure 15-1. Interrupt Sources

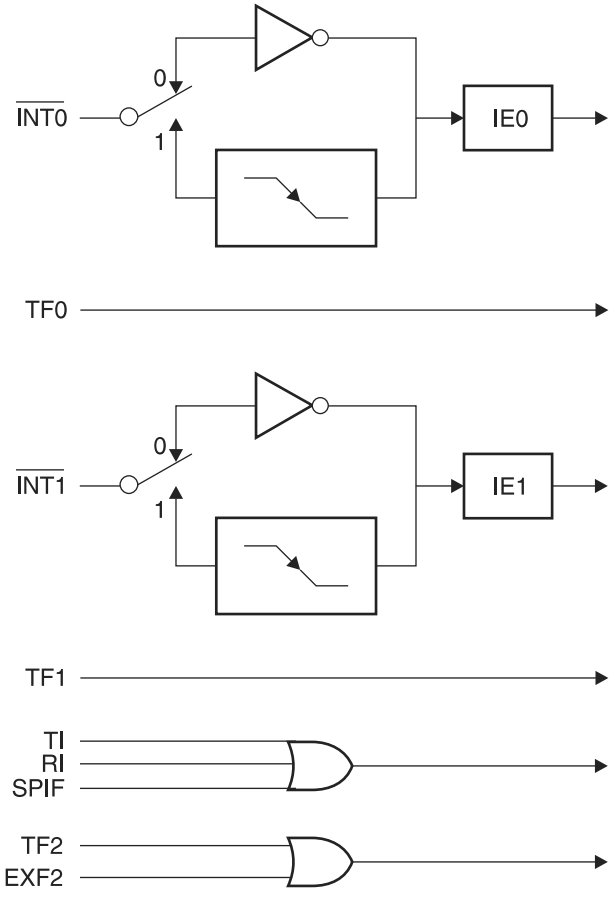
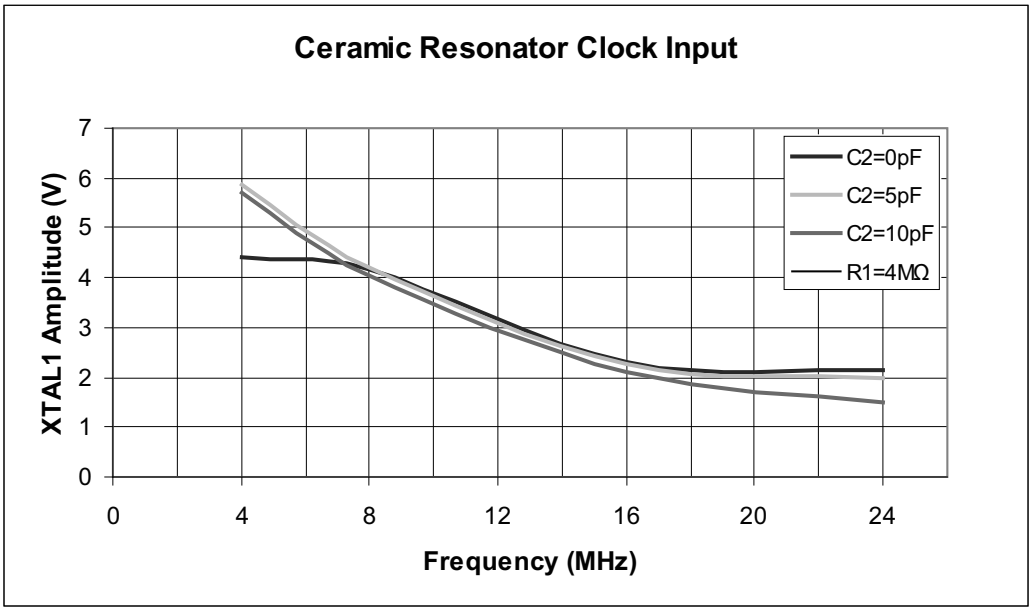
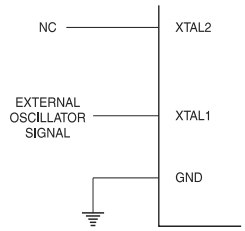


Figure 16-5. Ceramic Resonator Clock Source (B)



To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven, as shown in Figure 16-6.

Figure 16-6. External Clock Drive Configuration



17. Idle Mode

In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. This mode is invoked by software. The content of the on-chip RAM and all the special functions registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

Note that when idle mode is terminated by a hardware reset, the device normally resumes program execution from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when idle mode is terminated by a reset, the instruction following the one that invokes idle mode should not write to a port pin or to external memory.

10. Repeat steps 4 through 7 changing the address and data for the entire array or until the end of the object file is reached.
11. Power-off sequence:
    a. Tri-state the address and data inputs.
    b. Disable the P3.0 pullup used for RDY/$\overline{\text{BUSY}}$ operation.
    c. Set XTAL1 to “L”.
    d. Set RST and $\overline{\text{EA}}$ pins to “L”.
    e. Turn V_{CC} power off.

$\overline{\text{Data}}$ Polling: The AT89S8253 features $\overline{\text{DATA}}$ Polling to indicate the end of any programming cycle. During a write cycle in the parallel or serial programming mode, an attempted read of the last loaded byte will result in the complement of the written datum on P0.7 (parallel mode), and on the MSB of the serial output byte on MISO (serial mode). Once the write cycle has been completed, true data are valid on all outputs, and the next cycle may begin. $\overline{\text{DATA}}$ Polling may begin any time after a write cycle has been initiated.

Ready/$\overline{\text{Busy}}$: The progress of byte programming in the parallel programming mode can also be monitored by the RDY/$\overline{\text{BSY}}$ output signal. Pin P3.0 is pulled Low after ALE goes High during programming to indicate $\overline{\text{BUSY}}$. P3.0 is pulled High again when programming is done to indicate READY. P3.0 needs an external pullup (typical 10 KΩ) when functioning as RDY/$\overline{\text{BSY}}$.

Program Verify: If lock bits LB1 and LB2 have not been programmed, the programmed Code or Data byte can be read back via the address and data lines for verification. The state of the lock bits can also be verified directly in the parallel and serial programming modes.

Chip Erase: Both Flash and EEPROM arrays are erased electrically at the same time. In the parallel programming mode, Chip Erase is initiated by using the proper combination of control signals. The code and data arrays are written with all “1”s during the Chip Erase operation. The User Row will also be erased if the UsrRowProEn fuse (Fuse3) = 0 (enabled state).

In the serial programming mode, a chip erase operation is initiated by issuing the Chip Erase instruction. In this mode, Chip Erase is self-timed and also takes about 8 ms.

During Chip Erase, a serial read from any address location will return 00H at the data outputs.

Serial Programming Fuse: A programmable fuse is available to disable Serial Programming if the user needs maximum system security. The Serial Programming Fuse can be disabled via both the Parallel/Serial Programming Modes, but can only be enabled via the Parallel mode.

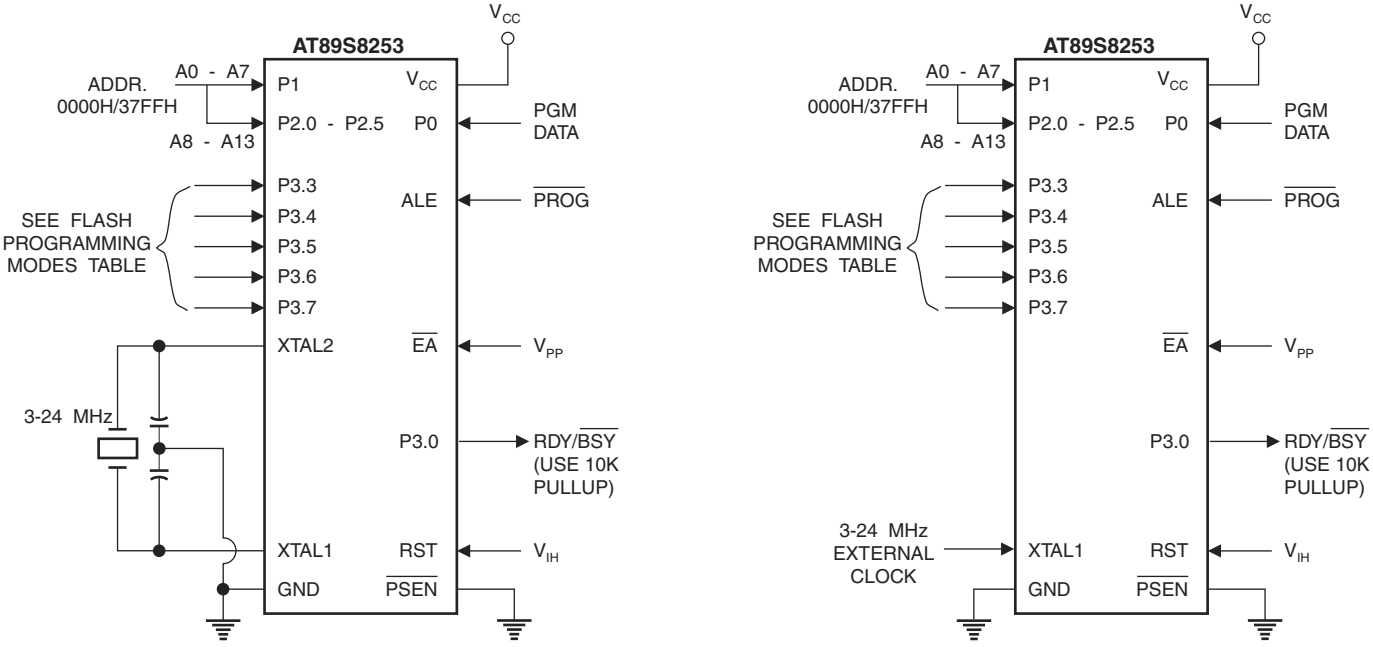
The AT89S8253 is shipped with the Serial Programming Mode enabled.

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 030H and 031H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows:

(030H) = 1EH indicates manufactured by Atmel
(031H) = 73H indicates AT89S8253

Fuse3 (User Row Access Fuse): This fuse enables/disables writing to the programmable user row.
Fuse4 (Clock Selection Fuse): This fuse selects between an external clock source and a quartz crystal as the clock input.

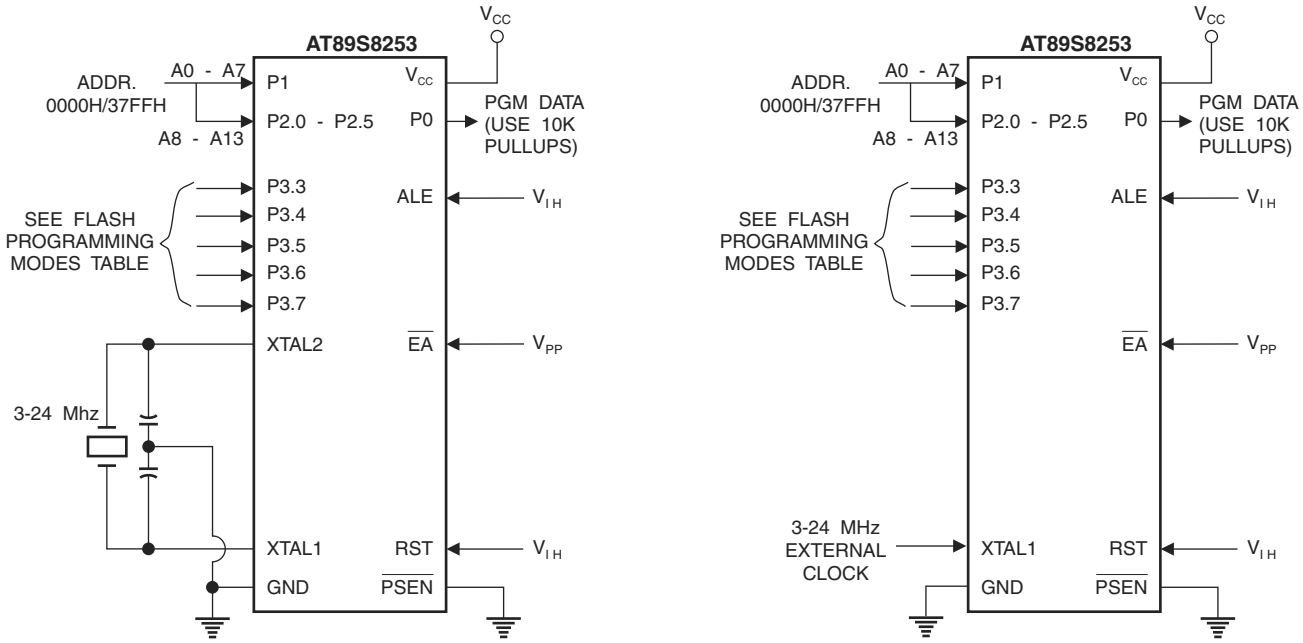
Programming the Flash/EEPROM Memory **(Parallel Mode)**



Oscillator Bypass Fuse (Fuse4) Off

Oscillator Bypass Fuse (Fuse4) On

Figure 25-2. Verifying the Flash/EEPROM Memory **(Parallel Mode)**



Oscillator Bypass Fuse (Fuse4) Off

Oscillator Bypass Fuse (Fuse4) On

Figure 25-3. Flash/EEPROM **Serial Downloading**

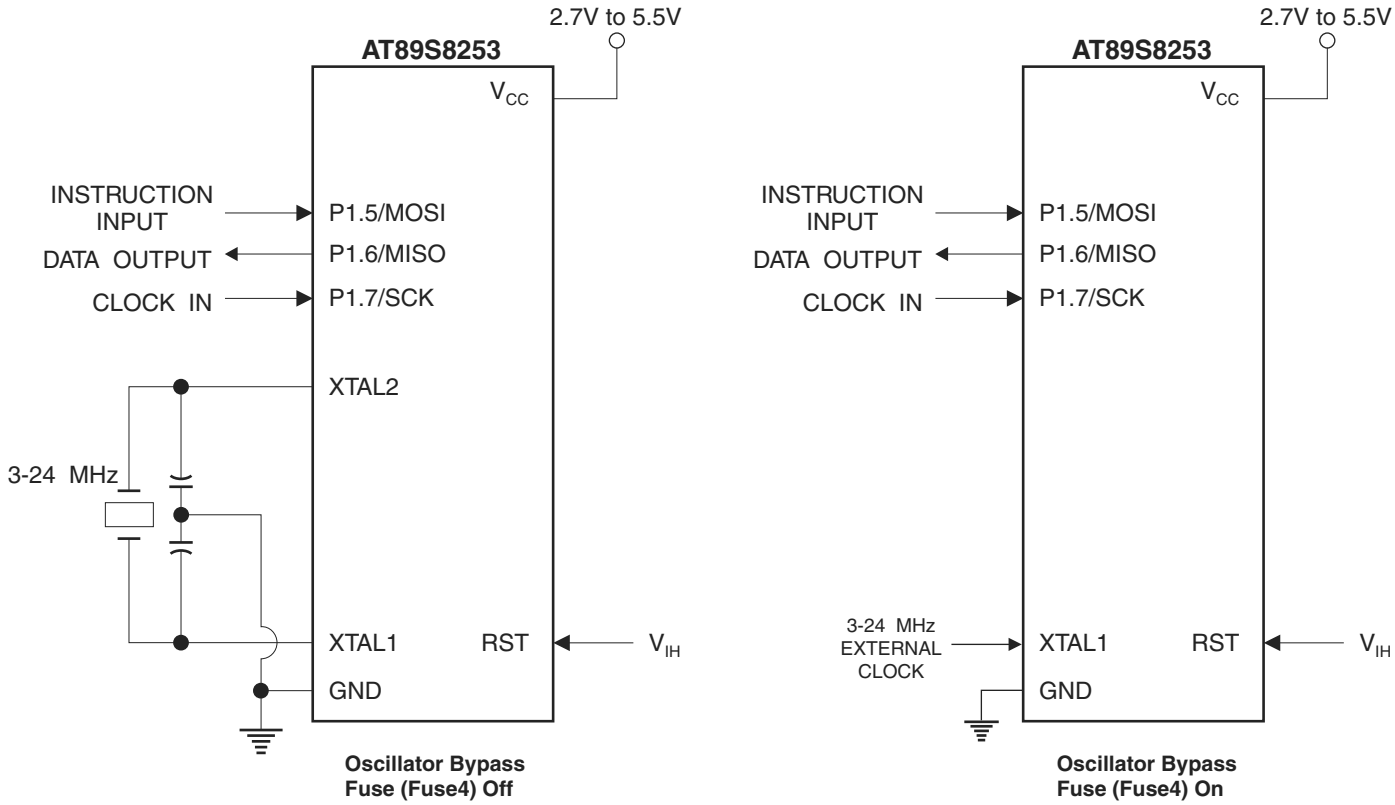
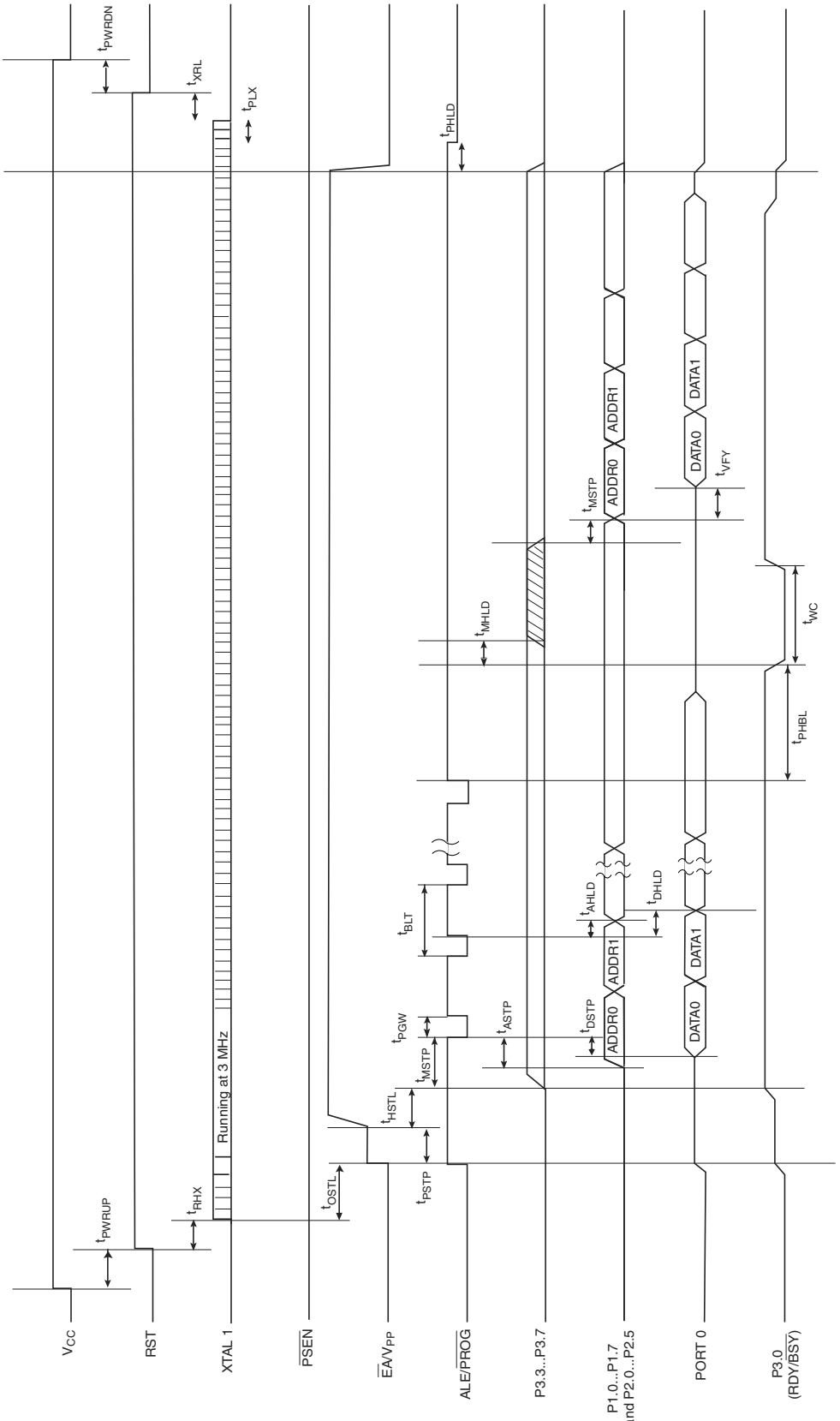


Figure 26-1. Flash/EEPROM Programming and Verification Waveforms – Parallel Mode



29. Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-1.0V to +7.0V
Maximum Operating Voltage	6.6V
DC Output Current	15.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

30. DC Characteristics

The values shown in this table are valid for T_A = -40°C to 85°C and V_{CC} = 2.7 to 5.5V, unless otherwise noted

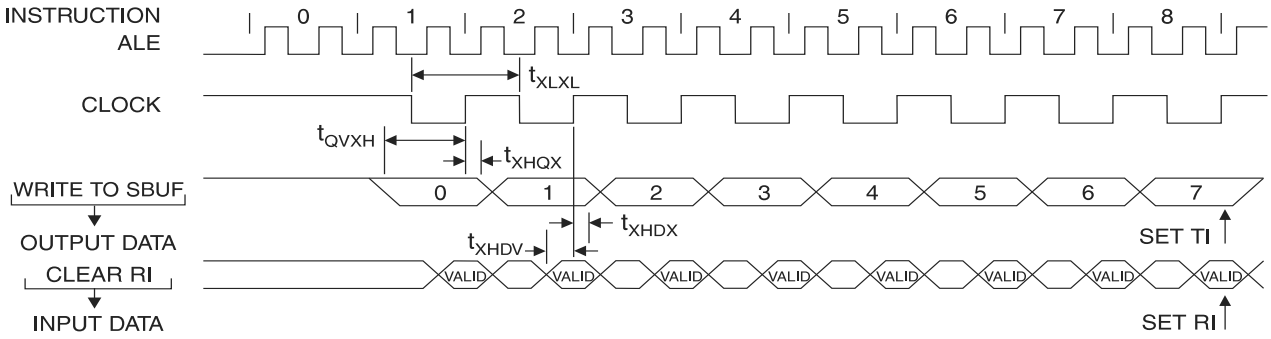
Symbol	Parameter	Condition	Min	Max
V_{IL}	Input Low-voltage	(Except $\overline{EA}$, XTAL1, RST, Port 0)	-0.5V	0.2 V_{CC} - 0.1V
V_{IL1}	Input Low-voltage	($\overline{EA}$, XTAL1, RST, Port 0)	-0.5V	0.3 V_{CC}
V_{IH}	Input High-voltage	(Except $\overline{EA}$, XTAL1, RST, Port 0)	0.5 V_{CC}	V_{CC} + 0.5V
V_{IH1}	Input High-voltage	($\overline{EA}$, XTAL1, RST, Port 0)	0.7 V_{CC}	V_{CC} + 0.5V
V_{OL}	Output Low-voltage[1]	I_{OL} = 10 mA, V_{CC} = 4.0V, T_A = 85°C		0.5V
V_{OH}	Output High-voltage When Weak Pull Ups are Enabled (Ports 1, 2, 3, ALE, $\overline{PSEN}$)	I_{OH} = -60 µA, T_A = 85°C	2.4V	
		I_{OH} = -25 µA, T_A = 85°C	0.75 V_{CC}	
		I_{OH} = -10 µA, T_A = 85°C	0.9 V_{CC}	
V_{OH1}	Output High-voltage When Strong Pull Ups are Enabled (Port 0 in External Bus Mode, P1, 2, 3, ALE, $\overline{PSEN}$)	I_{OH} = -40 mA, T_A = 85°C	2.4V	
		I_{OH} = -25 mA, T_A = 85°C	0.75 V_{CC}	
		I_{OH} = -10 mA, T_A = 85°C	0.9 V_{CC}	
I_{IL}	Logical 0 Input Current (Ports 1, 2, 3)	V_{IN} = 0.45V, V_{CC} = 5.5V, T_A = -40°C		-50 µA
I_{TL}	Logical 1 to 0 Transition Current (Ports 1, 2, 3)	V_{IN} = 2V, V_{CC} = 5.5V, T_A = -40°C		-352 µA
I_{LI}	Input Leakage Current (Port 0, $\overline{EA}$)	0.45V< V_{IN} < V_{CC}		±10 µA
RRST	Reset Pull-down Resistor		50 KΩ	150 KΩ
C_{IO}	Pin Capacitance	Test Freq. = 1 MHz, T_A = 25°C		10 pF
I_{CC}	Power Supply Current	Active Mode, 12 MHz, V_{CC} = 5.5V, T_A = -40°C		10 mA
		Idle Mode, 12 MHz, V_{CC} = 5.5V, T_A = -40°C		3.5 mA
	Power-down Mode[2]	V_{CC} = 5.5V, T_A = -40°C		100 µA
		V_{CC} = 4.0V, T_A = -40°C		20 µA

Notes:
1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 10 mA,
   Maximum I_{OL} per 8-bit port:15 mA,
   Maximum total I_{OL} for all output pins: 71 mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
2. Minimum V_{CC} for Power-down is 2V.

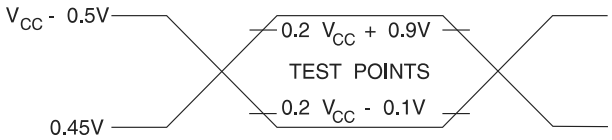
37. Serial Port Timing: Shift Register Mode Test Conditions

Symbol	Parameter	Variable Oscillator		Units
		Min	Max	

38. Shift Register Mode Timing Waveforms

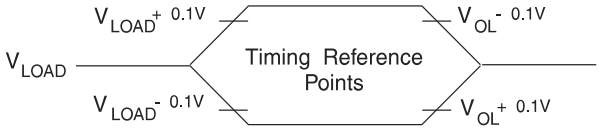


39. AC Testing Input/Output Waveforms(1)

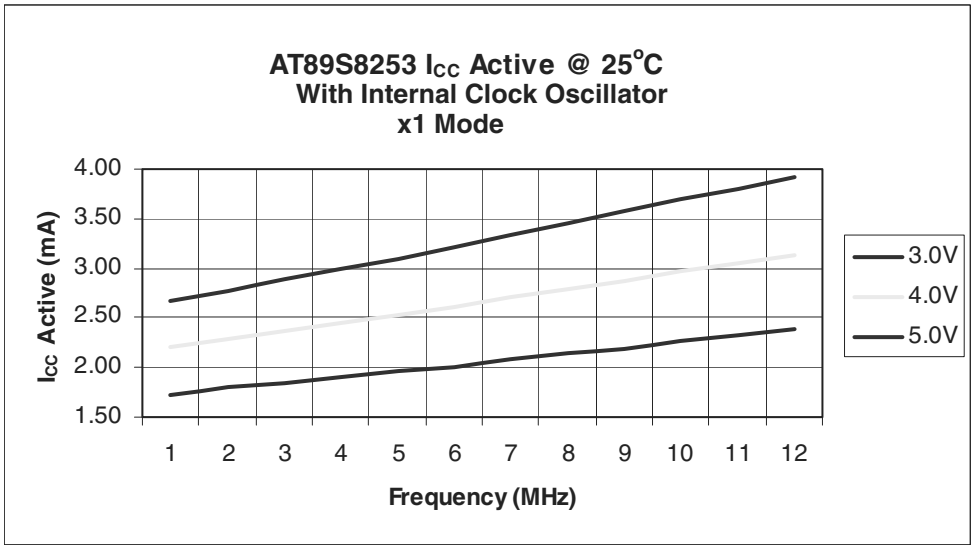


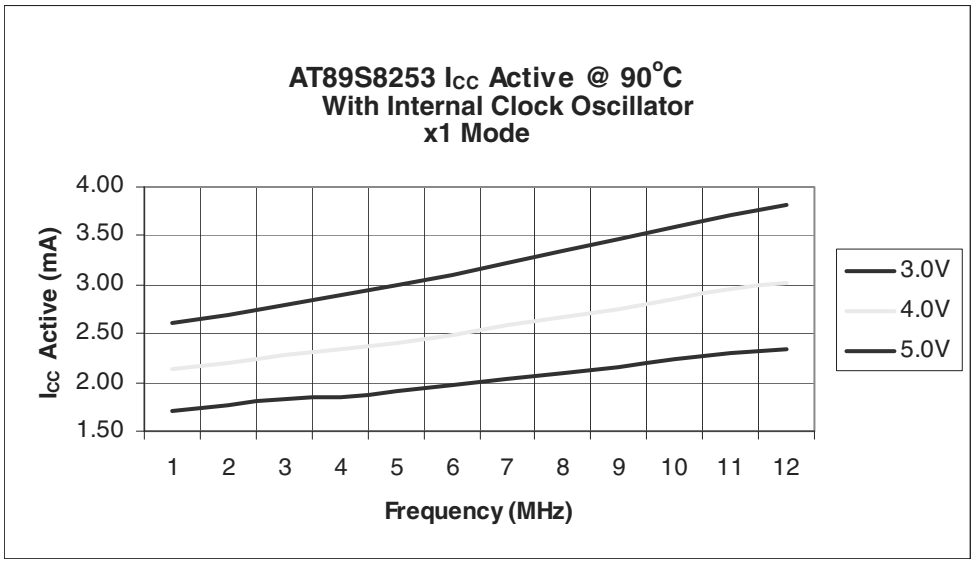
Note: 1. AC Inputs during testing are driven at V_{CC} - 0.5V for a logic 1 and 0.45V for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

40. Float Waveforms(1)

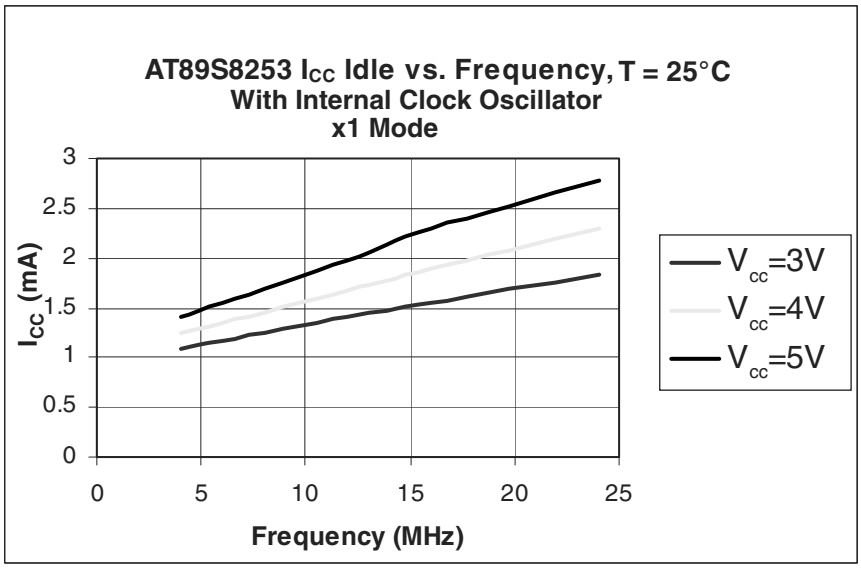


45. I_{CC} (Active Mode) Measurements

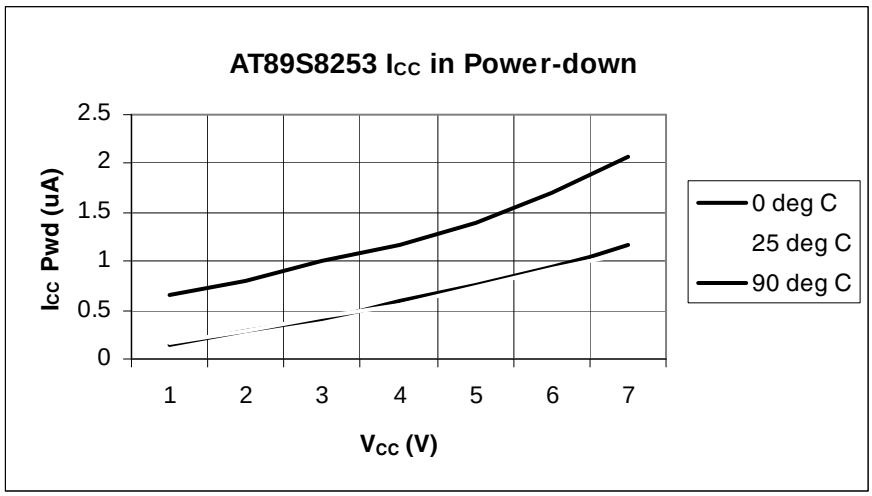




46. I_{CC} (Idle Mode) Measurements

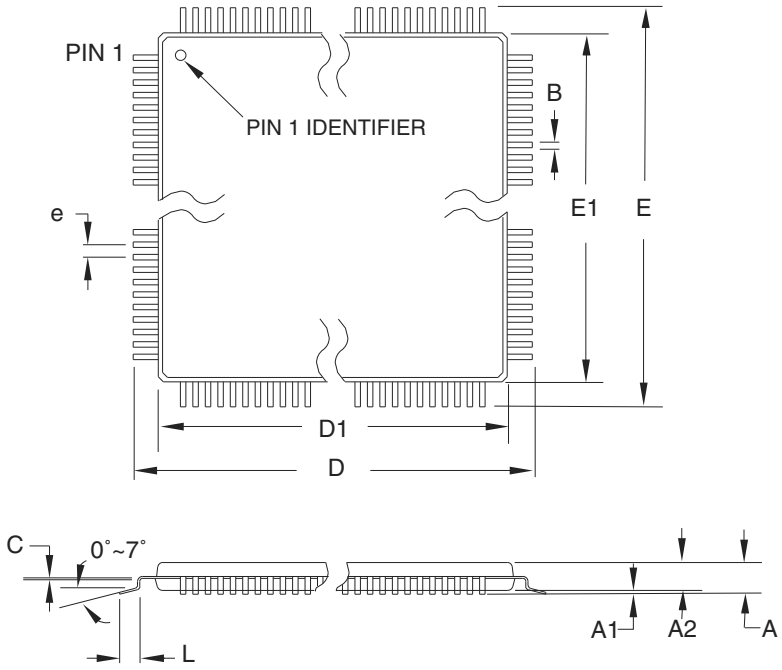


47. I_{CC} (Power Down Mode) Measurements



49. Package Information

49.1 44A – TQFP



COMMON DIMENSIONS
(Unit of Measure = mm)

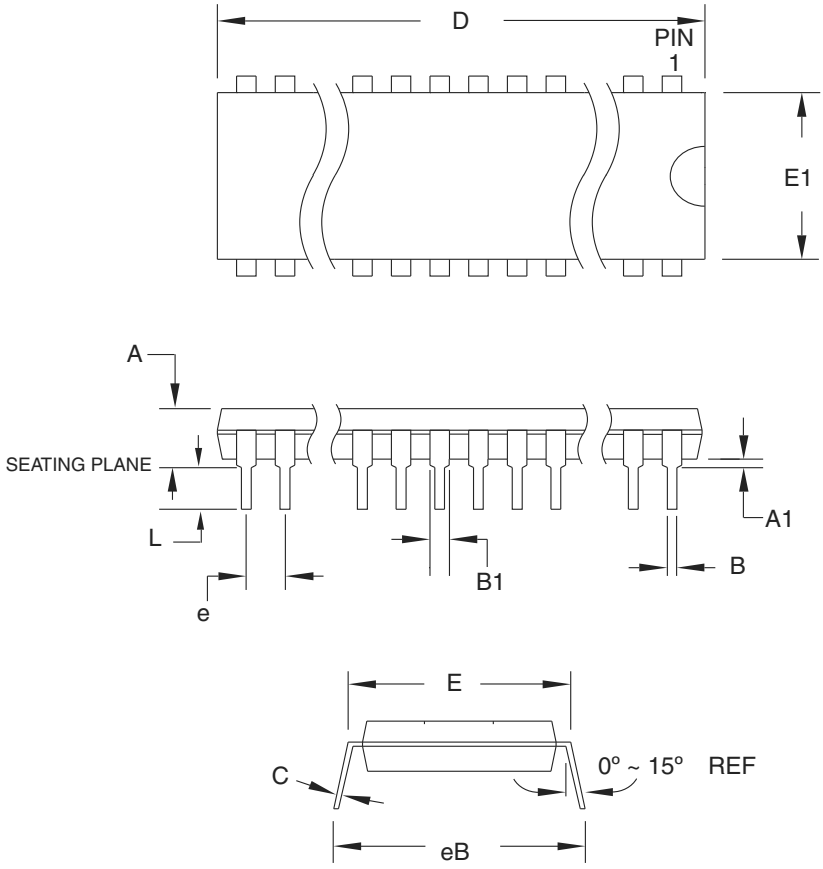
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
E	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
B	0.30	–	0.45	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.80 TYP			

Notes:
1. This package conforms to JEDEC reference MS-026, Variation ACB.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10 mm maximum.

10/5/2001

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44A,** 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	44A	B

49.3 40P6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = mm)

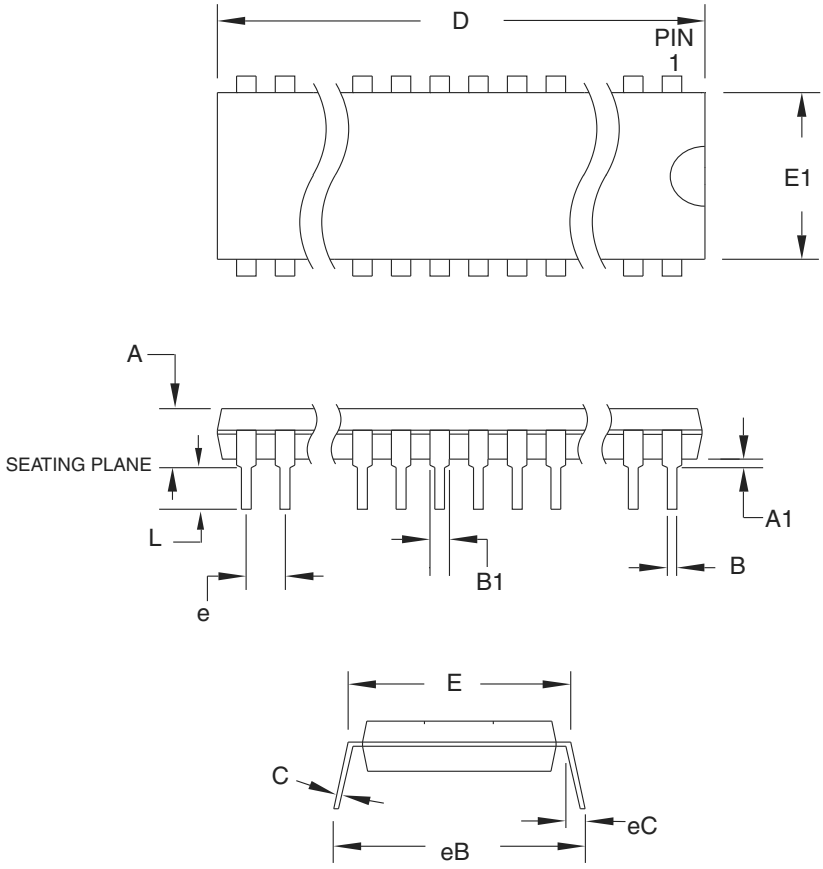
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	4.826	
A1	0.381	–	–	
D	52.070	–	52.578	Note 2
E	15.240	–	15.875	
E1	13.462	–	13.970	Note 2
B	0.356	–	0.559	
B1	1.041	–	1.651	
L	3.048	–	3.556	
C	0.203	–	0.381	
eB	15.494	–	17.526	
e	2.540 TYP			

Notes: 1. This package conforms to JEDEC reference MS-011, Variation AC.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

09/28/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**40P6**, 40-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	40P6	B

49.4 42PS6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = Inch)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	0.200	
A1	0.020	–	–	
D	1.440	1.450	1.460	Note 2
E	0.600	–	0.630	
E1	0.500	0.540	0.570	Note 2
B	0.015	0.018	0.022	
B1	0.035	0.040	0.045	
L	0.100	0.130	0.140	
C	0.009	0.010	0.015	
eB	–	–	0.730	
eC	0.000	–	0.060	
e	0.70 TYP			

Notes: 1. This package conforms to JEDEC reference MS-020, Variation AB.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

11/3/06

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**42PS6**, 42-lead (Shrink 0.070"/0.600" Row Space) Plastic Dual Inline Package (PDIP)	42PS6	B